

Serial No. 09/726,142

In the Specification:

Please amend the DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENT section of the specification by replacing the first full paragraph on page 9 with the following new paragraph to include the following new paragraph:

In Fig. 2, a cross-sectional view of the molded heat transfer part 10 of the present invention is shown while Fig. 3 illustrates a side elevational view of the part mounted 10 on a device 16 to be cooled. As best seen in Fig. 2, the molded heat transfer part 10 includes a heat conductive polymer core 13. An EMI and RF reflective coating 14 is applied, preferably on the entire outer surface 18 of the part. The molded heat transfer part 10 is net-shape molded, such as by injection molding, into a unitary structure from thermally conductive material, such as a thermally conductive polymer composition. The thermally conductive polymer composition includes a base polymer of, for example, a liquid crystal polymer that is loaded with a conductive filler material, such as copper flakes or carbon fiber (not shown). Carbon fiber is preferred because it cannot transfer electricity yet is still highly thermally conductive. Details of the polymer composition itself are not shown as they are well known in the art. Specifically, in the prior art of record, US Patent No. 6,251,978 describes loading a polymer composition with a PITCH based carbon fiber filler (Col. 6, lines 16-21) and US Patent No. 6,487,073 describes the preferred use of a PITCH based carbon fiber (Col. 6, lines 42-44). The EMI and RF reflective coating 14 is preferably nickel-copper. Other base materials and reflective coatings may be used and still be within the scope of the present invention. Also, the heat transfer part 10 of the present invention is net-shape molded which means that after molding it is ready for use and does not require additional machining or tooling to achieve the desired configuration of the part 10.